


PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	CRP/24/13832	
1.3 Title of PCI	D2PAK/H2PAK Carrier tape design robustness improvement	
1.4 Product Category	Refer to impacted product list	
1.5 Issue date	2024-03-05	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	KRAUSE INA
2.1.2 Phone	+49 89460062370
2.1.3 Email	ina.krause@st.com
2.2 Change responsibility	
2.2.1 Process Owner	Chiara ZACCHERINI
2.2.2 Corporate Quality Manager	Gerard PETIT

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	Any indirect material modifications for shipping products in dimensions, material, composition, orientation	ST Shenzhen

4. Description of change

	Old	New
4.1 Description	Carrier tape current design (refer to detailed description with schematic)	Carrier tape new design (refer to detailed description with schematic) : - Add a platform on the pocket bottom : it will have the better strength than the flat bottom pocket - Increase the thickness of the carrier tape from T=0.30mm to T=0.35mm
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	Form : No change on product Fit : No change on product Function : No change on product Reliability : No change on product Processability : No change on product	

5. Reason / motivation for change

5.1 Motivation	For quality continuous improvement, the design of the carrier tape is enhanced to prevent lead deformation.
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Date-code - Internal Traceability
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7. Timing / schedule

7.1 Date of qualification results	2024-01-02
7.2 Intended start of delivery	2024-06-03
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	13832 PCI D2PAK-H2PAK Carrier tape design robustness improvement_W07.pdf
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8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2024-03-05
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9. Attachments (additional documentations)			
13832 Public product.pdf			
13832 PCI D2PAK-H2PAK Carrier tape design robustness improvement_W07.pdf			

10. Affected parts		
10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	ACST610-8G	
	L4940D2T12-TR	
	L7806ABD2T-TR	
	L7806CD2T-TR	
	L7808CD2T-TR	
	LD1085D2M18R	
	LD1085D2M33R	
	LD1086D2TTR	
	LDP01-26AY	
	LDP01-30AY	
	LDP01-68AY	
	STB100N6F7	
	STB13N60M2	
	STB13N80K5	
	STB15N80K5	
	STB18N65M5	
	STB20N95K5	
	STB26N60M2	
	STB28N65M2	
	STB32NM50N	
	STB45N60DM2AG	
	STB80NF55-08AG	
	STB9NK80Z	
	STH270N8F7-2	
	STH275N8F7-6AG	
	STH6N95K5-2	
	STPS10150CG-TR	
	STPS10L40CG-TR	
	STPS16H100CG-TR	
	STPS20L60CG-TR	
	STPS30170CG-TR	
	STTH12R06G	
	STTH1512GY-TR	
	STTH15L06G-TR	
	STTH3002CG-TR	
	STTH30R03CG-TR	
	STTH810G-TR	
	STTH810GY-TR	
	STTH8R04G-TR	
	2STBN15D100	
	BUB941ZTT4	
2851909	FERD30H60CG-TR	

	FERD60H100CGY-TR	
3387270	SCTH100N65G2-7AG	
3387271	SCTH35N65G2V-7	
3764233	SCTH35N65G2V-7AG	
	SCTH40N120G2V-7	
	SCTH60N120G2-7	
	SCTH70N120G2V-7	
	STB100N10F7	
	STB100NF04T4	
	STB10NK60ZT4	
	STB13007DT4	
	STB130N6F7	
	STB140NF75T4	
2531102	STB18N60DM2	
	STB18NM80	
	STB24N60DM2	
2980909	STB24N60M6	
	STB25N80K5	
	STB30N65DM6AG	
	STB30N65M2AG	
	STB30NF20L	
	STB33N60DM2	
	STB33N65M2	
	STB34N65M5	
2987018	STB36N60M6	
	STB40NF10LT4	
	STB45N65M5	
	STB46NF30	
2980942	STB47N60DM6AG	
	STB55NF06T4	
	STB57N65M5	
	STB60NF06LT4	
	STB6N60M2	
	STB6N80K5	
	STB75NF75LT4	
	STB80N20M5	
	STB9NK60ZT4	
	STGB10NB37LZT4	
2809292	STGB20N45LZAG	
	STGB20NB41LZT4	
	STGB30M65DF2	
	STGB40H65FB	
	STGB40V60F	
	STGB7NC60HDT4	
3581062	STH10N80K5-2AG	
	STH200N10WF7-2	
3527138	STH2N120K5-2AG	
3011599	STH47N60DM6-2AG	
	STPS40150CG	
3105987	STPSC12065G2Y-TR	
3105988	STPSC8H065G2Y-TR	

	STTH3002CG	
	STTH30R04G	
3105991	STTH30RQ06G2-TR	
	SCT040H65G3AG	
	STH3N150-2	

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